

### **PATENTS**

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jack Oon Chu, et al.

**Docket: 17177A** 

Patent No: 6,858,502

Dated: July 15, 2005

Issued: February 22, 2005

For: HIGH SPEED COMPOSITE P-CHANNEL SI/

SIGE HETEROSTRUCTUR FOR FIELD

**EFFECT DEVICE** 

**Commissioner of Patents** P.O. Box 1450 **Alexandria, VA 22313-1450** 

following respects:

Certificate

JUL 2 2 2005

of Correction

### REQUEST FOR CERTIFICATE OF CORRECTION

Sir:

It appearing that errors have been introduced in the course of printing the

Patent issued in the above application,

it is respectfully requested that the Commissioner issue a Certificate of Correction in the

Column 1, Line 23:

"(HFMTs)" should read -- (HEMTs) --

Column 2, Line 27:

"Si<sub>1-x</sub>Gew" should read -- Si<sub>1-w</sub>Gew --

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### **Column 12, Line 19:**

"Si<sub>1-w</sub>Gex" should read -- Si<sub>1-w</sub>Gew --

# **Column 13, Line 29:**

"below the a channel" should read -- below a channel --

### **Column 14, Line 46:**

"layer fanned" should read -- layer formed above --

### Column 14, Line 49:

"method of fanning" should read -- method of forming --

## **Column 15, Line 24:**

"dram electrode" should read -- drain electrode --

It is further noted that additional errors typographical in nature are incorporated into the printed specification, but are believed to be satisfactorily clear in the context and accordingly it is simply requested that this paper be made of record in the file for such clarification as may be appropriate. They are as follows:

# Column 3, Line 61:

"Field effect" should read --field-effect --

# Column 6, Line 42:

"Si<sub>0..65</sub>Ge<sub>0.35</sub>" should read -- Si<sub>0.65</sub>Ge<sub>0.35</sub> -

Respectfully submitted,

Leslie S. Szivos Reg. No. 39,394

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# UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO

6,858,502

**APPLICATION NO: 09/989,770** 

**ISSUE DATE** 

February 22, 2005

INVENTOR(S)

: Jack Oon Chu, et al.

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

### Column 1, Line 23:

"(HFMTs)" should read -- (HEMTs) --

#### Column 2, Line 27:

"Si<sub>1-x</sub>Gew" should read -- Si<sub>1-w</sub>Gew --

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"dram electrode" should read -- drain electrode --

MAILING ADDRESS OF SENDER:

PATENT NO. 6,858,502

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